

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Currently Amended) A substrate with a microstructure formed thereon, the substrate comprising:

a temporary substrate supporting an upper substrate ;

a buffer layer formed on an upper surface of the temporary substrate to have a plurality of shapes with air gaps defined between each of said shapes and spaced apart from each other at regular intervals; and

an adhesive layer formed between the upper substrate and the buffer layer so that the upper substrate is adhered to the temporary substrate ~~[[via]]~~ by the adhesive layer and the buffer layer;

wherein, the upper substrate is a plastic, or a metal foil, or a very-thin substrate which is thin relative to the temporary substrate, and has a substantially higher flexibility than that of the temporary substrate, and on which a device is formed;

~~wherein the buffer layer is not a component of the device which is formed on the upper substrate; and~~

~~wherein~~ the temporary substrate ~~[[and]]~~ along with the air gaps ~~[[are]]~~ is adapted to be removed from the upper substrate after the manufacturing process of the device; and the air gaps facilitate the removal of the temporary substrate.

2. (Original) The substrate as claimed in claim 1, wherein the temporary substrate is made of at least one of Si, SiO.sub.2, Al.sub.2O.sub.3, copper, copper alloy, aluminum, aluminum alloy, and glass.

3. (Original) The substrate as claimed in claim 1, wherein the buffer layer is made of at least one of SiO.sub.2, Al.sub.2O.sub.3, AlON, SiON, Si.sub.3N.sub.4,

AIN, SOG (spin-on-glass), photosensitive material, Cu, Cu alloy, Al, and Al alloy.

4. (Original) The substrate as claimed in claim 1, wherein the buffer layer is patterned and etched to form a plurality of shapes arranged in many rows or to form a plurality of shapes arranged in hexahedron or cylindrical islands, with air gaps being spaced apart from each other at regular intervals.

5. (Original) The substrate as claimed in claim 1, wherein the adhesive layer is made of any one of a double sided tape, a liquid adhesive, and organic film, to withstand a hot process of more than 100.degree. C.

6. (Original) The substrate as claimed in claim 1, wherein the upper substrate is made of any one of plastic, stainless steel, copper, copper alloy, aluminum, aluminum alloy, silicon, and glass.

7-12. (Cancelled)

13. (New) A substrate with a microstructure formed thereon, the substrate comprising:

a temporary substrate having an upper surface and a lower surface, said upper surface defining a plurality of projections; and

an adhesive layer adhering a lower surface of an upper substrate to the lower substrate along said projections;

wherein, a plurality of air gaps are defined in between each of said projections, thereby minimizing stress applied to the upper substrate and the lower substrate during a manufacturing process of a semiconductor device or the like.

14. (New) The substrate according to claim 13, wherein, said temporary substrate is a multi layer structure.